

# FMV20N50E

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3</sup> series

# **N-CHANNEL SILICON POWER MOSFET**

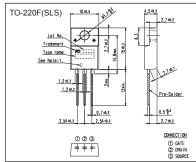
#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (3.0±0.5V) High avalanche durability

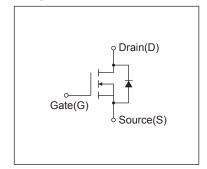
## Applications

Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

# ■ Outline Drawings [mm]



# **■** Equivalent circuit schematic



## Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks	
Drain Course Voltoge	V <sub>DS</sub>	500	V		
Drain-Source Voltage	V <sub>DSX</sub>	500	V	V <sub>GS</sub> = -30V	
Continuous Drain Current	ID	±20	А		
Pulsed Drain Current	I <sub>DP</sub>	±80	Α		
Gate-Source Voltage	Vgs	±30	V		
Repetitive and Non-Repetitive Maximum Avalanche Current	Iar	20	Α	Note*1	
Non-Repetitive Maximum Avalanche Energy	Eas	582.5	mJ	Note*2	
Repetitive Maximum Avalanche Energy	Ear	9.5	mJ	Note*3	
Peak Diode Recovery dV/dt	dV/dt	7.4	kV/μs	Note*4	
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5	
Maniana Bana Biasiastias	Б	2.16	10/	Ta=25°C	
Maximum Power Dissipation	P□	95	W	Tc=25°C	
O	Tch	150	°C		
Operating and Storage Temperature range	T <sub>stg</sub>	-55 to +150	°C		
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz	

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions	Conditions		typ.	max.	Unit
Drain-Source Breakdown Voltage	BVoss	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		500	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	In=250µA, Vns=Vs	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.0	3.5	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =10A, V <sub>GS</sub> =10V		-	0.27	0.31	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =10A, V <sub>DS</sub> =25V	I <sub>D</sub> =10A, V <sub>DS</sub> =25V		22	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	2650	3980	pF
Output Capacitance	Coss	V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		250	375	
Reverse Transfer Capacitance	Crss	f=1MHz -		-	19	28.5	
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>GS</sub> =10V I <sub>D</sub> =10A R <sub>GS</sub> =10Ω		-	22	33	ns
	tr			-	11	16.5	
Turn-Off Time	td(off)			-	120	180	
	tf			-	21	31.5	
Total Gate Charge	QG	Vcc=250V		-	77	115.5	nC
Gate-Source Charge	Qss	ID=20A	ID=20A		17	25.5	
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V		-	22	33	
Avalanche Capability	lav	L=1.07mH, Tch=25°C	L=1.07mH, Tch=25°C		-	-	Α
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =20A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°	I <sub>F</sub> =20A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		0.90	1.35	V
Reverse Recovery Time	trr	I <sub>F</sub> =20A, V <sub>GS</sub> =0V	I <sub>F</sub> =20A, V <sub>GS</sub> =0V		0.5	-	μs
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	7	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to Case			1.320	°C/W
	Rth (ch-a)	Channel to Ambient			58.0	°C/W

Note \*1 : Tch≤150°C

Note \*2 : Stating Tch=25°C, Ias=8A, L=16.7mH, Vcc=50V, R<sub>G</sub>=50Ω

Eas limited by maximum channel temperature and avalanche current.

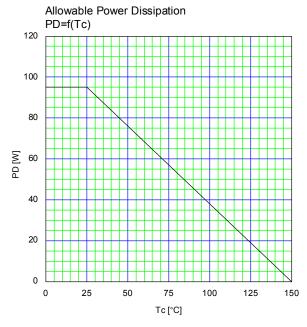
See to 'Avalanche Energy' graph.

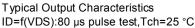
Note  ${}^{\star}3$  : Repetitive rating : Pulse width limited by maximum channel temperature.

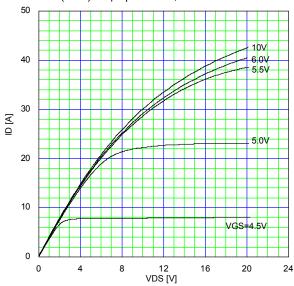
See to the 'Transient Themal impeadance' graph.

Note \*4 : I₅≤-I₀, -di/dt=100A/μ₅, Vcc≤BVbss, Tch≤150°C.

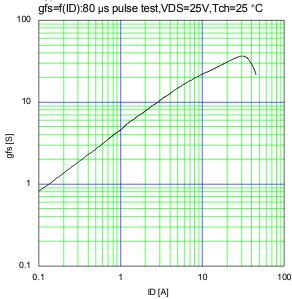
Note \*5 : I₅≤-I₀, dv/dt=7.4kV/μ₅, Vcc≤BVbss, Tch≤150°C.



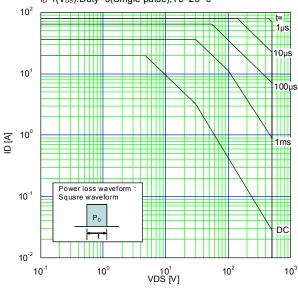




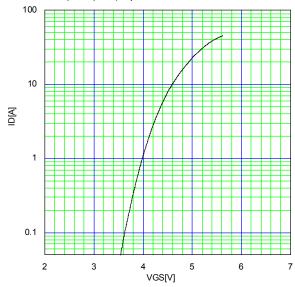
Typical Transconductance
afs=f(ID):80 us pulse test.VDS=25V.Tch=25 °C



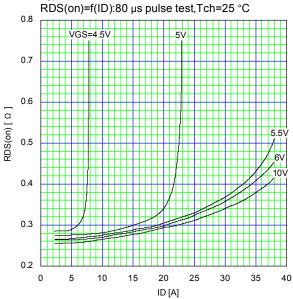
Safe Operating Area I<sub>D</sub>=f(V<sub>DS</sub>):Duty=0(Single pulse),Tc=25 °c

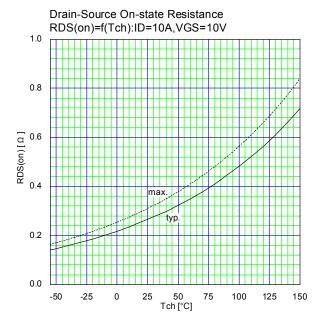


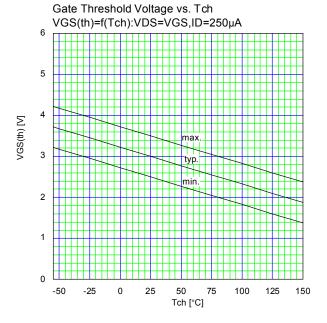
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C

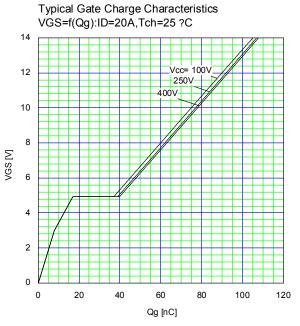


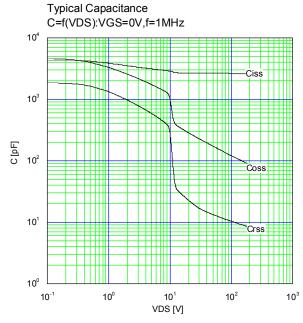
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 us pulse test.Tch=25 °C

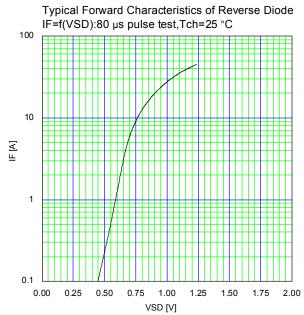


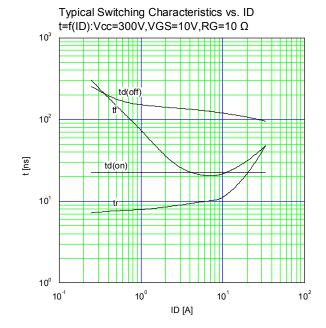


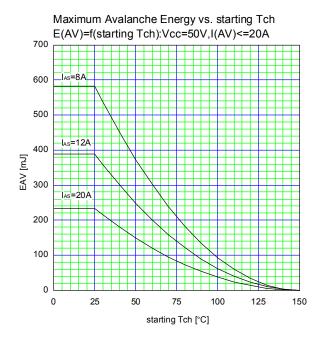


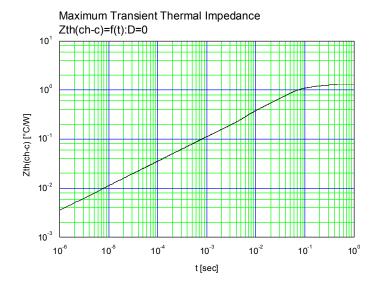












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